

CIRCUPOSIT™ 7800

Desmear/Electroless Copper for Semi-additive Process

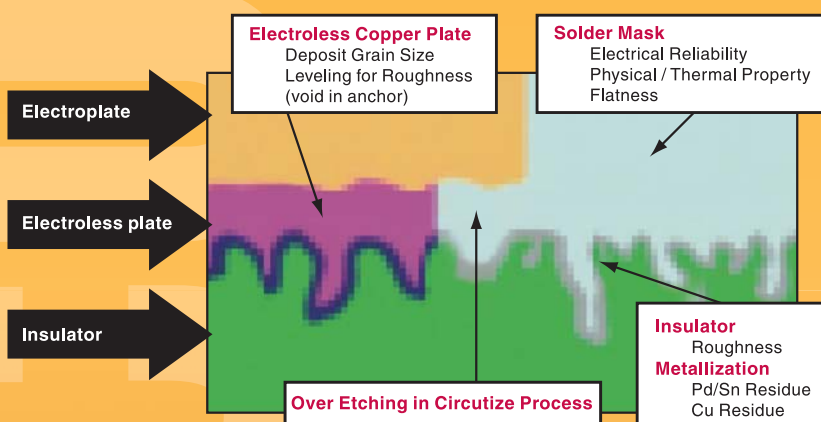
Description

CIRCUPOSIT™ 7800 desmear process provides optimal pretreatment on all hole-wall surfaces thus ensuring consistently superior coverage, adhesion and solderability. This process, used in conjunction with Dow Electronic Materials' electroless copper and electroplate processes, delivers excellent reliability for high-end chip packaging.

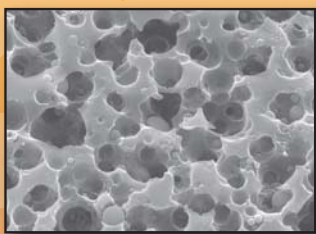
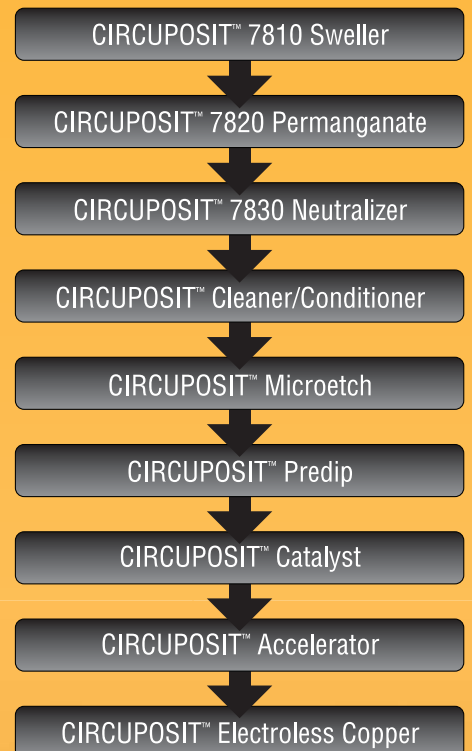
Features and Benefits

- Uniform and stable adhesion promotion treatment and reliable via bottom cleaning
- Stable and wide process window
- High peel strength and optimum surface roughness for resist adhesion
- Excellent plating coverage on insulator and via
- Excellent electrical reliability with high insulation resistance

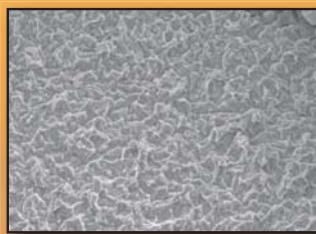
Key Issue for SAP



Process



Adhesion promotion on insulator



Via Bottom Cleaning



Excellent Plating coverage



Cu-Cu Connection